Adhesive Mechanism

Chemical effect

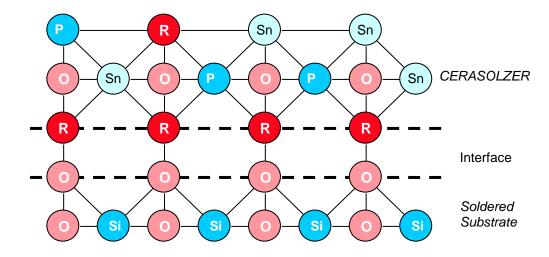
with active solder alloy "CERASOLZER" (valid for soldering on glass, ceramics and metal oxides)

Although it is quite difficult to completely explain the mechanism of how CERASOLZER adheres to materials, these mechanisms are qualitatively understood as follows:

Since the adhesive property of CERASOLZER is essentially based upon the characteristics of the alloy, the ultrasonic vibration is merely applied to help its bonding process. CERASOLZER contains a little amount of such elements as Zn, Ti, Si, Al, Be, and Rare Earth which have a strong chemical affinity with oxygen. these metals are thought, during the bonding process, to combine with oxygen in air to form oxide, which is chemically bound to the surface of the glass, ceramics, metal oxide, etc. Thus, CERASOLZER bonding process proceeds under the liquid-solid reaction between oxides themselves. Such adhesive mechanism has been already confirmed in other areas of glass-metal bonding such as vacuum tube sealing.

Accordingly, if oxygen is completely eliminated by substituting the air surrounding the bonding equipment with an inactive gas, e.g., nitrogen, the adhesive power of CERASOLZER will be lost. It has been experimentally found that the critical oxygen concentration for adhesive power is about 2%.

A model of chemical binding between CERASOLZER and the substrate is illustrated below.



When quartz glass is used, the metallic oxides (R, O), which are components of CERASOLZER **unite chemically** with the SiO₂ (M) of glass.

Alloy # GS155 Melting Point (C°)

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Specific Gravity	7,1
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Content	%
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Alloy # GS182

Melting Point (C°)	145 ~ 203
Specific Gravity	7,1

Content	%
Tin	70 ~ 80
Antimony	3 ~ 5
Zinc	
Indium	15 ~ 25
Al, Ti, Si, Cu	



Alloy # GS217

Melting Point (C ⁰).	199 ~ 217
Specific Gravity	7,3

Content	%
Tin	94 ~ 96
Antimony	3 ~ 5
Zinc	
Al, Ti, Si, Cu	



Alloy # CS186

Melting Point (C°)	186	Eutectic
Specific Gravity	8,9	

Content	%
Tin	60
Lead	35
Zinc	

Antimony Al, Ti, Si, Cu

Alloy # CS224 Melting Point (C°) Specific Gravity Content Tin Lead Zinc Antimony AI, Ti, Si, Cu	9,7 % 40	Eutectic
Alloy # CS246 Melting Point (C°) Specific Gravity Content Tin Lead Zinc Antimony Al, Ti, Si, Cu	10,1 % 30	Eutectic
Alloy # CS297 Melting Point (C°) Specific Gravity Content Tin Lead Zinc Antimony Al, Ti, Si, Cu	10,2 % 5	Eutectic
Alloy # GS-200ALU Melting Point (C°) Specific Gravity Content Tin	7,3 % 85	Eutectic RoHS 2002/95/EC

Alloy # GS220

Melting Point (C°)	221-230
Specific Gravity	

Content	
Sn	92
Ti	3
Ag	3
Ce, Ga, Sb, Cu, In, As, Ni, Zn	Rest / Balance
Pb	<0,001
Cd	<0,001
Fe	< 0.001

